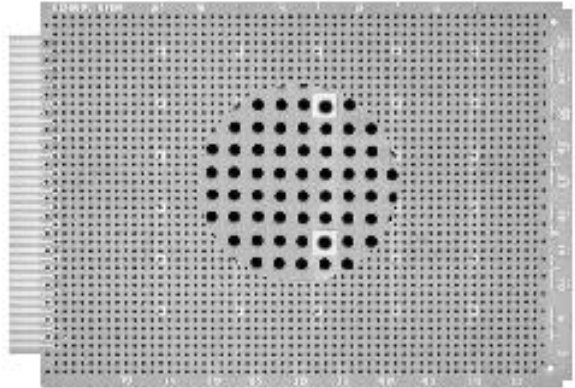


3719-1**4.5" x 6.5"**

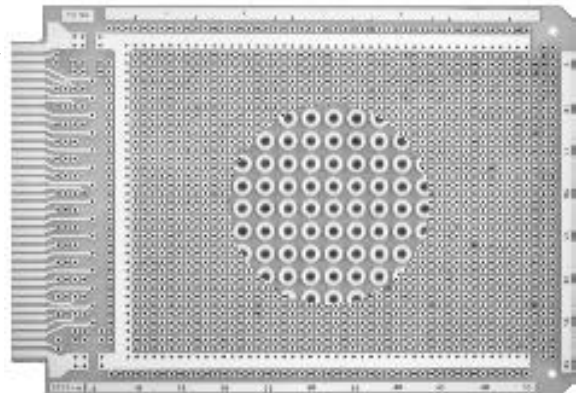
Circuit Pattern: Contacts Only
Contacts: 36/72 @ .100" Ctrs,
Ni/Gold
Width/Thick: 6.50"/.062"
Height: 4.50"
16-Pin DIP Capacity: 50
Material: CEM-1
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R636-2
Extender: 3690-4
Rec. Card Cage: Series 13
Wire-Wrap Connector: R636-1
Hole Diameter: .042"

- *Unrestricted component placement over entire board surface*
- *Layout paper and instructions included*
- *Row and column legends provided*

**3719-6****4.5" x 6.5"**

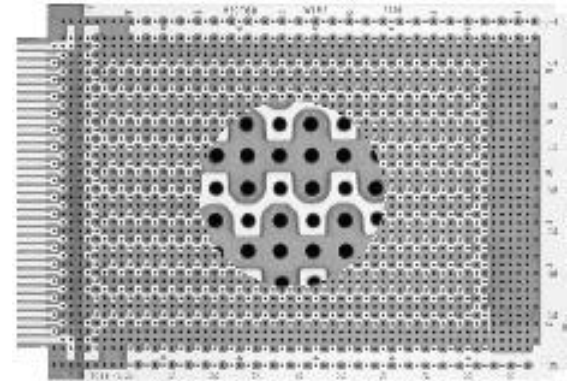
Circuit Pattern: Pad-Per-Hole
Contacts: 36/72 @ .100" Ctrs,
Ni/Gold
Width/Thick: 6.50"/.062"
Height: 4.50"
16-Pin DIP Capacity: 40
Material: FR4 Epoxy Glass
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R636-2
Extender: 3690-4
Rec. Card Cage: Series 13
Wire-Wrap Connector: R644-1
Hole Diameter: .042"

- *0.080" diameter, isolated solder pad around holes, plated-thru holes*
- *Low resistance, etched peripheral bus pattern*
- *Pad and bus surfaces solder-coated for user convenience*
- *Convenient, easy-to-read hole marking legend on board surface*
- *Layout paper and instructions included*

**4066-4****4.5" x****6.5"**

Circuit Pattern: Ground Plane/
Interleaved Buses
Contacts: 36/72 @ .100" Ctrs,
Ni/Gold
Width/Thick: 6.50"/.062"
Height: 4.50"
16-Pin DIP Capacity: 34
Material: CEM-1
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R636-2
Extender: 3690-4
Rec. Card Cage: Series 13
Wire-Wrap Connector: R636-1
Hole Diameter: .042"

- *Overall ground plane on wiring side; etched, interleaved zig-zag bus pattern on component side provides three bus lines for ECL circuitry*
- *0.085" etched clearance area around each hole on ground plane side*
- *Bus and plane surfaces solder-coated for user convenience*
- *Layout paper and instructions included*

**3719-4****4.5" x 9.6"**

Circuit Pattern: Contacts Only
Contacts: 36/72 @ .100" Ctrs,
Ni/Gold
Width/Thick: 9.60"/0.62"
Height: 4.50"
16-Pin DIP Capacity: 90
Material: CEM-1
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Solder Connector: R636-2
Extender: 3690-2
Rec. Card Cage: Series 14
Wire-Wrap Connector: R636-1
Hole Diameter: .042"

- *Unrestricted component placement over entire board surface*
- *Row and column legends provided*
- *Layout paper and instructions included*

